

ABSTRACT

The present invention discloses an electroplating apparatus, comprising: a membrane frame, the center of which is provided with a through hole; transport branch pipes, extending from the side wall of the through hole of the membrane frame to the edge of the membrane frame; a plating solution buffer structure, comprising a central cap and a flow stabilizing sleeve, the central cap being provided on the through hole of the membrane frame and covering the through hole; a plurality of first holes being formed on the top of the central cap, the flow stabilizing sleeve being fixed below the central cap and inserted in the through hole of the membrane frame, and at least one second hole being formed in the side wall of the flow stabilizing sleeve; and a diffusion plate being fixed to the top of the membrane frame and provided with a plurality of third holes. A cathode plating solution flows into the space between the flow stabilizing sleeve and the side wall of the through hole through the transport branch pipes, then enters the interior of the flow stabilizing sleeve through the second holes on the side wall of the flow stabilizing sleeve, and then is supplied to the diffusion plate through the first holes in the central cap and reaches the substrate through the third holes. The present invention can buffer the flow speed of the fluid, thus effectively solving the problem of differentiation between the center and the edge of the substrate to be electroplated, and improving the quality of the electroplating product.